

## 2-pack-integrated intelligent Power System

### Power section

#### SKiiP 2403GB122-4DW

##### Data

#### Power section features

- SKiiP technology inside
- SPT (Soft Punch Trough) IGBTs
- CAL diode technology
- Integrated current sensor
- Integrated temperature sensor
- Integrated heat sink
- IEC 60721-3-3 (humidity) class 3K3/IE32 (SKiiP® 3 System)
- IEC 60068-1 (climate) 40/125/56
- UL recognized File no. E63532

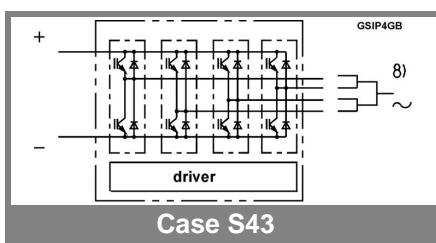
1) with assembly of suitable MKP capacitor per terminal

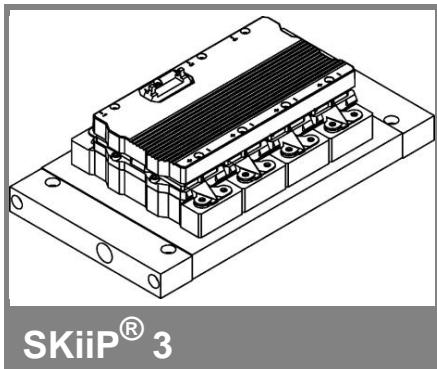
8) AC connection busbars must be connected by the user; copper busbars available on request

Absolute Maximum Ratings		$T_s = 25^\circ\text{C}$ unless otherwise specified		
Symbol	Conditions	Values		Units
<b>IGBT</b>				
$V_{CES}$		1200		V
$V_{CC}^1)$	Operating DC link voltage	900		V
$V_{GES}$		$\pm 20$		V
$I_C$	$T_s = 25 \text{ (70)}^\circ\text{C}$	2400 (1800)		A
<b>Inverse diode</b>				
$I_F = -I_C$	$T_s = 25 \text{ (70)}^\circ\text{C}$	1930 (1470)		A
$I_{FSM}$	$T_j = 150^\circ\text{C}$ , $t_p = 10 \text{ ms}$ ; sin	13500		A
$I^2t$ (Diode)	Diode, $T_j = 150^\circ\text{C}$ , 10 ms	911		kA <sup>2</sup> s
$T_j$ ( $T_{stg}$ )		- 40 ... + 150 (125)		°C
$V_{isol}$	rms, AC, 1 min, main terminals to heat sink	3000		V
$I_{AC\text{-terminal}}$	per AC terminal, rms, $T_s = 70^\circ\text{C}$ ,	400		A
	$T_{\text{terminal}} < 115^\circ\text{C}$			

Characteristics		$T_s = 25^\circ\text{C}$ unless otherwise specified		
Symbol	Conditions	min.	typ.	max.
<b>IGBT</b>				
$V_{CEsat}$	$I_C = 1200 \text{ A}$ , $T_j = 25 \text{ (125)}^\circ\text{C}$ ; measured at terminal	2,3 (2,5)	2,6	V
$V_{CEO}$	$T_j = 25 \text{ (125)}^\circ\text{C}$ ; at terminal	1,1 (1)	1,3 (1,2)	V
$r_{CE}$	$T_j = 25 \text{ (125)}^\circ\text{C}$ ; at terminal	1 (1,2)	1,1 (1,4)	mΩ
$I_{CES}$	$V_{GE} = 0 \text{ V}$ , $V_{CE} = V_{CES}$ , $T_j = 25 \text{ (125)}^\circ\text{C}$	4,8 (144)		mA
$E_{on} + E_{off}$	$I_C = 1200 \text{ A}$ , $V_{CC} = 600 \text{ V}$ $T_j = 125^\circ\text{C}$ , $V_{CC} = 900 \text{ V}$	360		mJ
$R_{CC+EE'}$	terminal chip, $T_j = 25^\circ\text{C}$	0,13		mΩ
$L_{CE}$	top, bottom	3		nH
$C_{CHC}$	per phase, AC-side	4		nF
<b>Inverse diode</b>				
$V_F = V_{EC}$	$I_F = 1200 \text{ A}$ , $T_j = 25 \text{ (125)}^\circ\text{C}$ measured at terminal	1,95 (1,7)	2,1	V
$V_{TO}$	$T_j = 25 \text{ (125)}^\circ\text{C}$	1,1 (0,8)	1,2 (0,9)	V
$r_T$	$T_j = 25 \text{ (125)}^\circ\text{C}$	0,7 (0,8)	0,8 (0,9)	mΩ
$E_{rr}$	$I_C = 1200 \text{ A}$ , $V_{CC} = 600 \text{ V}$ $T_j = 125^\circ\text{C}$ , $V_{CC} = 900 \text{ V}$	96		mJ
		122		mJ
<b>Mechanical data</b>				
$M_{dc}$	DC terminals, SI Units	6	8	Nm
$M_{ac}$	AC terminals, SI Units	13	15	Nm
w	SKiiP® 3 System w/o heat sink	3,1		kg
w	heat sink	9,7		kg
<b>Thermal characteristics (NWK40; 8l/min; 50%glycol); "s" reference to heat sink; "r" reference to built-in temperature sensor</b>				
$R_{th(j-s)I}$	per IGBT		0,013	K/W
$R_{th(j-s)D}$	per diode		0,025	K/W
$Z_{th}$	$R_i$ (mK/W) (max. values)		$\tau_{au}(s)$	
	1 2 3 4	1 2 3 4		
$Z_{th(j-r)I}$	1,2 5 5,8 0	69 0,35 0,02		1
$Z_{th(j-r)D}$	2 3 13,5 13,5	50 5 0,25		0,04
$Z_{th(r-a)}$	2,7 4,6 1,1 0,6	48 15 2,8		0,4

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## 2-pack-integrated intelligent Power System

**2-pack  
integrated gate driver  
SKiiP 2403GB122-4DW**

Data

### Gate driver features

- CMOS compatible inputs
- Wide range power supply
- Integrated circuitry to sense phase current, heat sink temperature and DC-bus voltage (option)
- Short circuit protection
- Over current protection
- Over voltage protection (option)
- Power supply protected against under voltage
- Interlock of top/bottom switch
- Isolation by transformers
- Fibre optic interface (option for GB-types only)
- IEC 60068-1 (climate) 40/85/56
- UL recognized file no. 242581

<b>Absolute Maximum Ratings</b>		$T_a = 25^\circ\text{C}$ unless otherwise specified	
<b>Symbol</b>	<b>Conditions</b>	<b>Values</b>	<b>Units</b>
$V_{S2}$	unstabilized 24 V power supply	30	V
$V_i$	input signal voltage (high)	15 + 0,3	V
$dv/dt$	secondary to primary side	75	kV/ $\mu\text{s}$
$V_{isolIO}$	input / output (AC, rms, 2s)	3000	V
$V_{isolPD}$	partial discharge extinction voltage, rms, $Q_{PD} \leq 10 \text{ pC}$	1170	V
$V_{isol12}$	output 1 / output 2 (AC, rms, 2s)	1500	V
$f_{sw}$	switching frequency	8	kHz
$f_{out}$	output frequency for $I_{peak(1)} = I_C$	8	kHz
$T_{op} (T_{stg})$	operating / storage temperature	- 40 ... + 85	°C

<b>Characteristics</b> ( $T_a = 25^\circ\text{C}$ )						
<b>Symbol</b>	<b>Conditions</b>	<b>min.</b>	<b>typ.</b>	<b>max.</b>		
$V_{S2}$	supply voltage non stabilized	13	24	30		
$I_{S2}$	$V_{S2} = 24 \text{ V}$	$324 + 39 * f/\text{kHz} + 0,00011 * (I_{AC}/A)^2$				
$V_{IT+}$	input threshold voltage (High)	12,3				
$V_{IT-}$	input threshold voltage (Low)	4,6				
$R_{IN}$	input resistance	10				
$C_{IN}$	input capacitance	1				
$t_{d(on)IO}$	input-output turn-on propagation time	1,3				
$t_{d(off)IO}$	input-output turn-off propagation time	1,3				
$t_{pERRRESET}$	error memory reset time	9				
$t_{TD}$	top / bottom switch interlock time	3,3				
$I_{analogOUT}$	max. 5mA; 8 V corresponds to 15 V supply voltage for external components	2000				
$I_{s1out}$	max. load current	50				
$I_{TRIPSC}$	over current trip level ( $I_{analog OUT} = 10 \text{ V}$ )	2500				
$T_{tp}$	over temperature protection	110	120			
$U_{DCTRIP}$	$U_{DC}$ -protection ( $U_{analog OUT} = 9 \text{ V}$ ); (option for GB types)	not implemented				

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